Technical Data *Green Poducts*
Data Sheet N1814, Rev. -

FTB6F-15FP THRU FTB10F-15FP
1.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Features:

- **Glass Passivated Chip Junction**
- **Reverse Voltage - 600 to 1000 V**
- **Forward Current - 1.5 A**
- **Designed for Surface Mount Application**
- **Fast reverse recovery time**
- **This is a Halogen Free Device**
- **All SMC parts are traceable to the wafer lot**
- **Additional testing can be offered upon request**

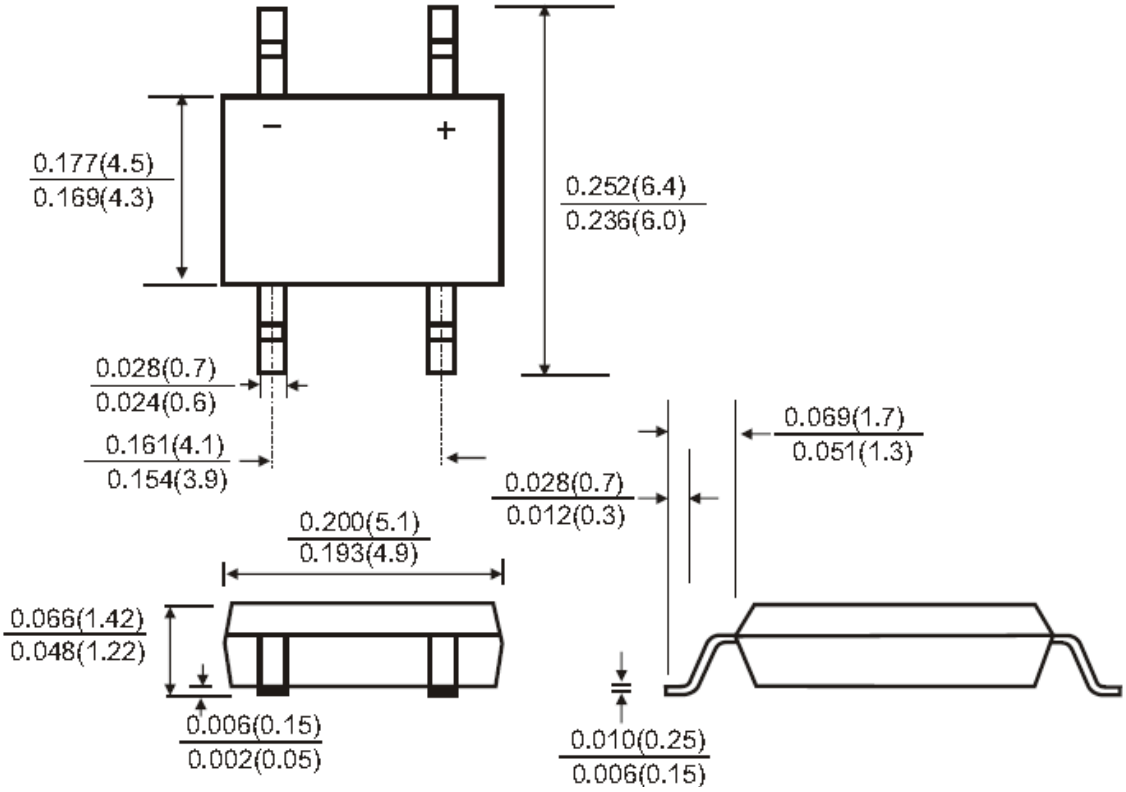
PIN	DESCRIPTION
1	Input Pin（~）
2	Input Pin（~）
3	Output Anode（+）
4	Output Cathode（-）



Mechanical Data:

- **Case: ABS/LBF**
- **Terminals: Solderable per MIL-STD-750, Method 2026**
- **Weight: 88 mg**

Mechanical Dimensions: In Inches/mm



ABS

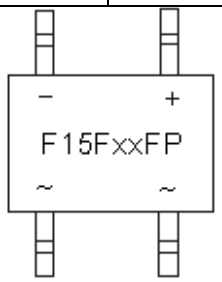
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Marking Diagram:

Type number	Marking code
FTB6F-15FP	F15F6FP
FTB8F-15FP	F15F8FP
FTB10F-15FP	F15F10FP



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	FTB6F -15FP	FTB8F -15FP	FTB10F -15FP	Units
Maximum repetitive peak reverse voltage	V_{RRM}	600	800	1000	V
Maximum RMS voltage	V_{RMS}	420	560	700	V
Maximum DC blocking voltage	V_{DC}	600	800	1000	V
Maximum Average Forward Rectified Current at T_A=75℃	$I_{F(AV)}$	1.5			A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50			A
Maximum Instantaneous Forward Voltage at 1.5A	V_F	1.3			V
Maximum DC reverse current T_A=25 ℃ at rated DC blocking voltage T_A=125 ℃	I_R	5.0 50			μA
Maximum Reverse Recovery Time (Note 3)	T_{rr}	160			ns
Typical Junction Capacitance (Note 1)	C_J	35			Pf
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	75			°C/W
Junction Temperature	T_J	-55 to +150			°C
Storage Temperature Range	T_{STG}	-55 to +150			°C

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm^2) copper pad.
3. Reverse Recovery Test Conditions: IF=0.5A, IR=1.0A, IRR=0.25A

Fig.1 Forward Current Derating Curve

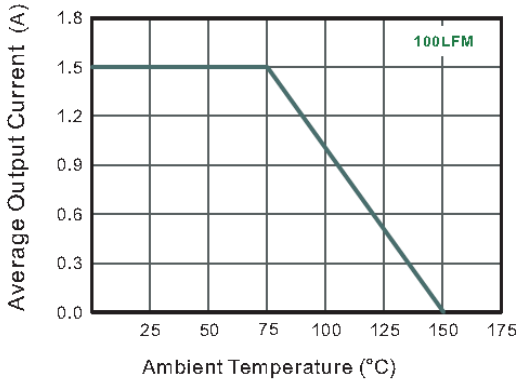


Fig.2 Typical Reverse Characteristics

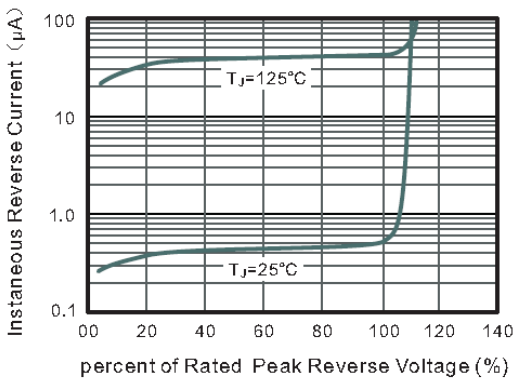


Fig.3 Typical Instaneous Forward Characteristics

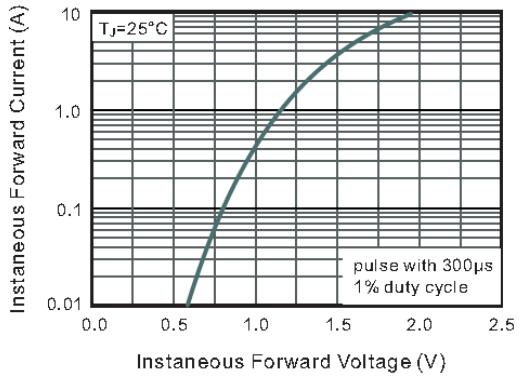


Fig.4 Typical Junction Capacitance

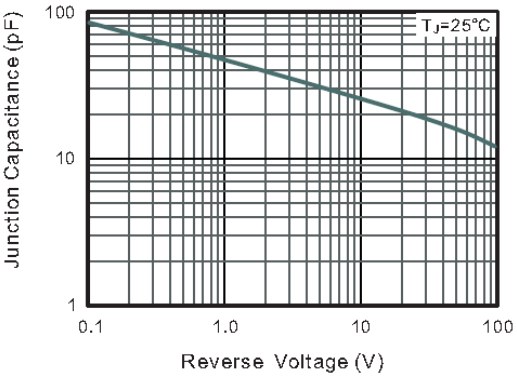
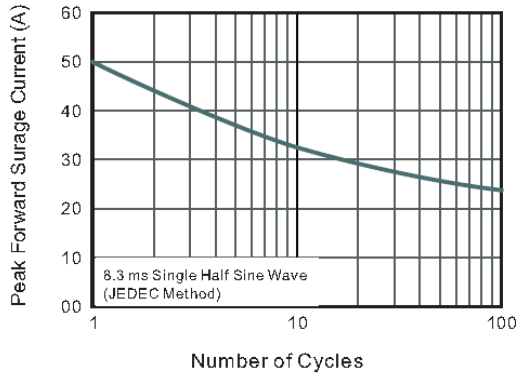


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current



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